

Abstract

The present invention provides a concept for anchoring fixed structural elements and in particular for anchoring electrodes 5 for components whose component structure is formed in a silicon layer (2) on top of a substrate (4) used as support. This concept is especially suitable for components manufactured from SOI wafers.

10 According to the present invention, the fixed element (6) is mechanically connected to the substrate (4) via at least one anchoring element (7) made of an anchoring material and extending through the silicon layer (2). In the case of an SOI wafer, the anchoring element (7) extends through the silicon 15 layer (2) and the sacrificial layer (3) of the SOI wafer. To this end, in the area of the surface of the fixed element (6), at least one recess is made in the silicon layer (2), which extends through the entire silicon layer (2) and the sacrificial layer (3) down to the substrate (4). The recess is 20 then filled with an anchoring material, so that the fixed element (6) is mechanically connected to the substrate (4) via the anchoring element (7) that is thereby created.

(Fig. 1)